PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5607184

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
WOOCHAN KIM	07/05/2019
VIVEK KISHORECHAND ARORA	07/05/2019
KEN PHAM	07/08/2019

RECEIVING PARTY DATA

Name:	TEXAS INSTRUMENTS INCORPORATED
Street Address:	12500 TI BOULEVARD
Internal Address:	M/S 3999
City:	DALLAS
State/Country:	TEXAS
Postal Code:	75243

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16504816

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone:	214-479-1230
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Correspondent Name:	TEXAS INSTRUMENTS INCORPORATED
Address Line 1:	P O BOX 655474, M/S 3999
Address Line 4:	DALLAS, TEXAS 75265

ATTORNEY DOCKET NUMBER:	TI-90394
NAME OF SUBMITTER:	NEIL R. JETTER
SIGNATURE:	/Neil R. Jetter/
DATE SIGNED:	07/08/2019

Total Attachments: 2

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Attorney Docket No.
TI-90394

Serial No. 16/504,816

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made.

WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefore, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set hand and seal this day and year;

TITLE OF INVENTION	STACKED DIE SEMICONDUCTOR PACKAGE
SIGNATURE OF INVENTOR AND NAME	Woochan Kim
DATE	07/05/2019
RESIDENCE (CITY AND STATE)	San Jose, CA

TITLE OF INVENTION	STACKED DIE SEMICONDUCTOR PACKAGE
SIGNATURE OF INVENTOR AND NAME	Vivek Kishorechand Arora
DATE	07/05/19.
RESIDENCE (CITY AND STATE)	San Jose, CA

TITLE OF INVENTION	STACKED DIE SEMICONDUCTOR PACKAGE
SIGNATURE OF INVENTOR AND NAME	Ken Pham
DATE	07/08/19
RESIDENCE (CITY AND STATE)	San Jose, CA

After recording, return Assignment to:

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265